

# Announcement and Call for Abstracts

IMAPS and SEMI Proudly announce a Joint Topical Workshop on

## Wire Bonding

[www.imaps.org/wirebonding](http://www.imaps.org/wirebonding)

July 15, 2010

Moscone Center

San Francisco, California - USA

**Abstract Deadline: April 30, 2010**

General Chair:	Wire Bonding Workshop Organizing Committee:		
<b>Lee Levine</b> Process Solutions Consulting New Tripoli, PA 18006 Phone: 610-248-2002 <a href="mailto:levilr@ptd.net">levilr@ptd.net</a>	<b>Joe Bubel</b>	Hesse & Knipps	<a href="mailto:bubel@hesse-knipps.us">bubel@hesse-knipps.us</a>
	<b>Bob Chylak</b>	KNS	<a href="mailto:bchylak@kns.com">bchylak@kns.com</a>
	<b>Mike McKeown</b>	Orthodyne Electronics	<a href="mailto:mike.mckeown@orthodyne.com">mike.mckeown@orthodyne.com</a>
	<b>Daniel Evans</b>	Palomar	<a href="mailto:devans@bonders.com">devans@bonders.com</a>
	<b>Leroy Christie</b>	ASM Pacific	<a href="mailto:Leroy.christie@asmpt.com">Leroy.christie@asmpt.com</a>

### Wire Bonding Workshop Focus:

The objective of Wire Bonding Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Microelectronic Packaging. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to Wire Bonding.

- Copper Ball Bonding and Bumping
- Cu/Low-K Processes and Materials
- Stacked Dies and 3-D Packaging
- Wire Bonding and Bumping
- Novel Packaging and Design
- Heavy Wire Bonding
- Failure Analysis and Reliability
- Electromigration and Interfacial Adhesion
- Testing and Probing Challenges
- Simulation and Modeling

Those wishing to present a paper at the Wire Bonding Topical Workshop must submit a 200-300 word abstract electronically **no later than April 30, 2010**, using the on-line submittal form at: [www.imaps.org/abstracts.htm](http://www.imaps.org/abstracts.htm). Full written papers are not required; however, an extended abstract of 1-4 pages is due for accepted presenters no later than June 18, 2010.

### Student Competition sponsored by *The Microelectronics Foundation*:



*The Microelectronics Foundation* sponsors Student Paper Competitions in conjunction with all Advanced Technology Workshops (ATWs) and Conferences. Students submitting their work and identifying that "**Yes, I'm a full-time student**" on the abstract submission form, will automatically be considered for these competitions. The review committee will evaluate all student papers/posters and award at least one student author with a \$1,000 check at the ATW/Conference. The selected student must attend the event to present his or her work and receive the award. The Foundation will return the registration fee for the winner. The winner must pay for travel and lodging expenses.

Please contact Jackki Morris-Joyner by email at [jmorris@imaps.org](mailto:jmorris@imaps.org) or by phone at 202-548-4001 if you have questions.

Accepted papers may be considered for publication in the *IMAPS Journal of Microelectronics and Electronic Packaging*. **All Speakers are required to pay a reduced registration fee and are required to attend the entire event.**

[www.imaps.org/wirebonding](http://www.imaps.org/wirebonding)